Microchip Technology - DSPIC33FJ32MC102T-I/SS Datasheet

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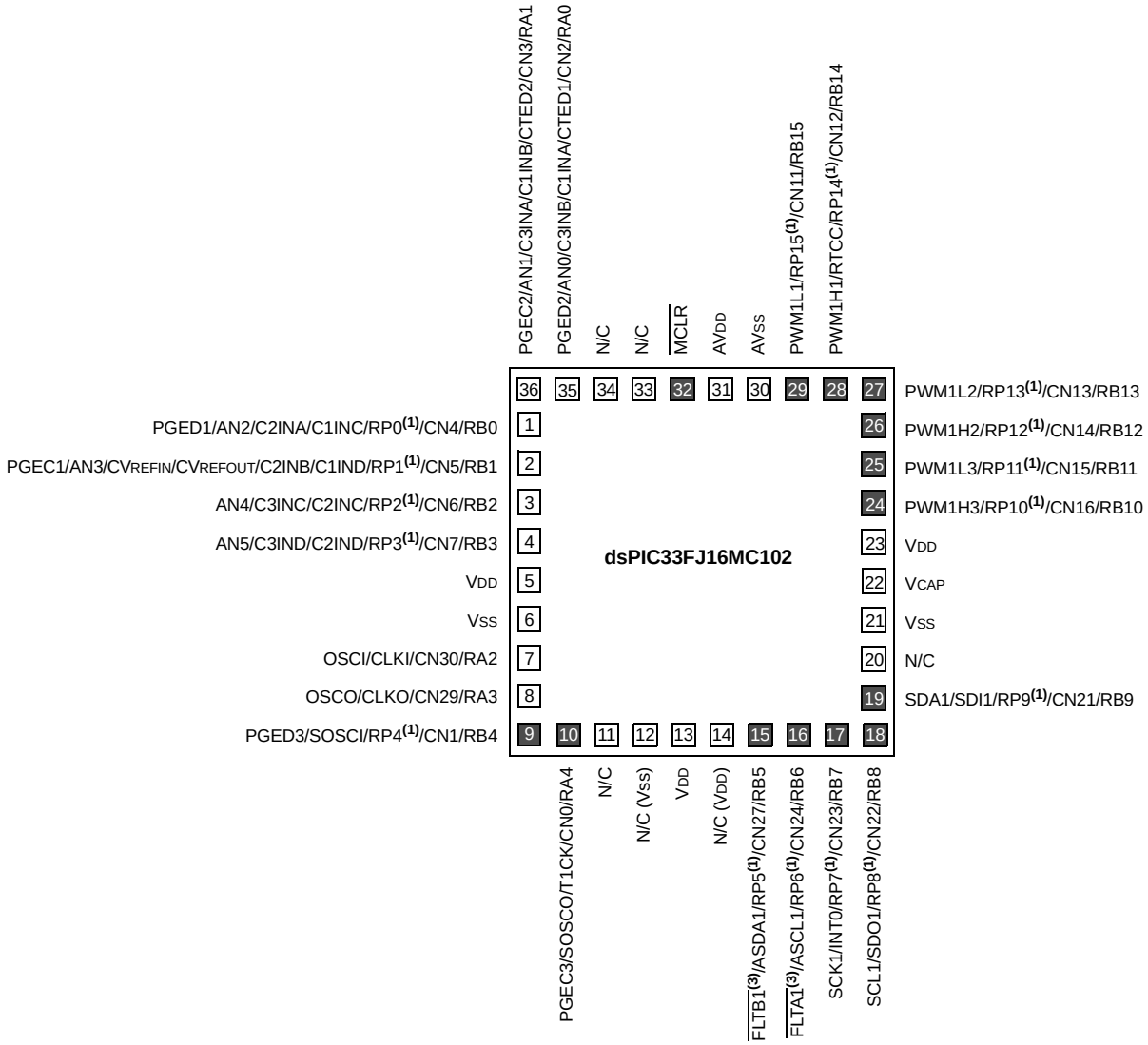
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	16 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj32mc102t-i-ss

Pin Diagrams (Continued)

36-Pin VTLA(2)

■ = Pins are up to 5V tolerant



Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

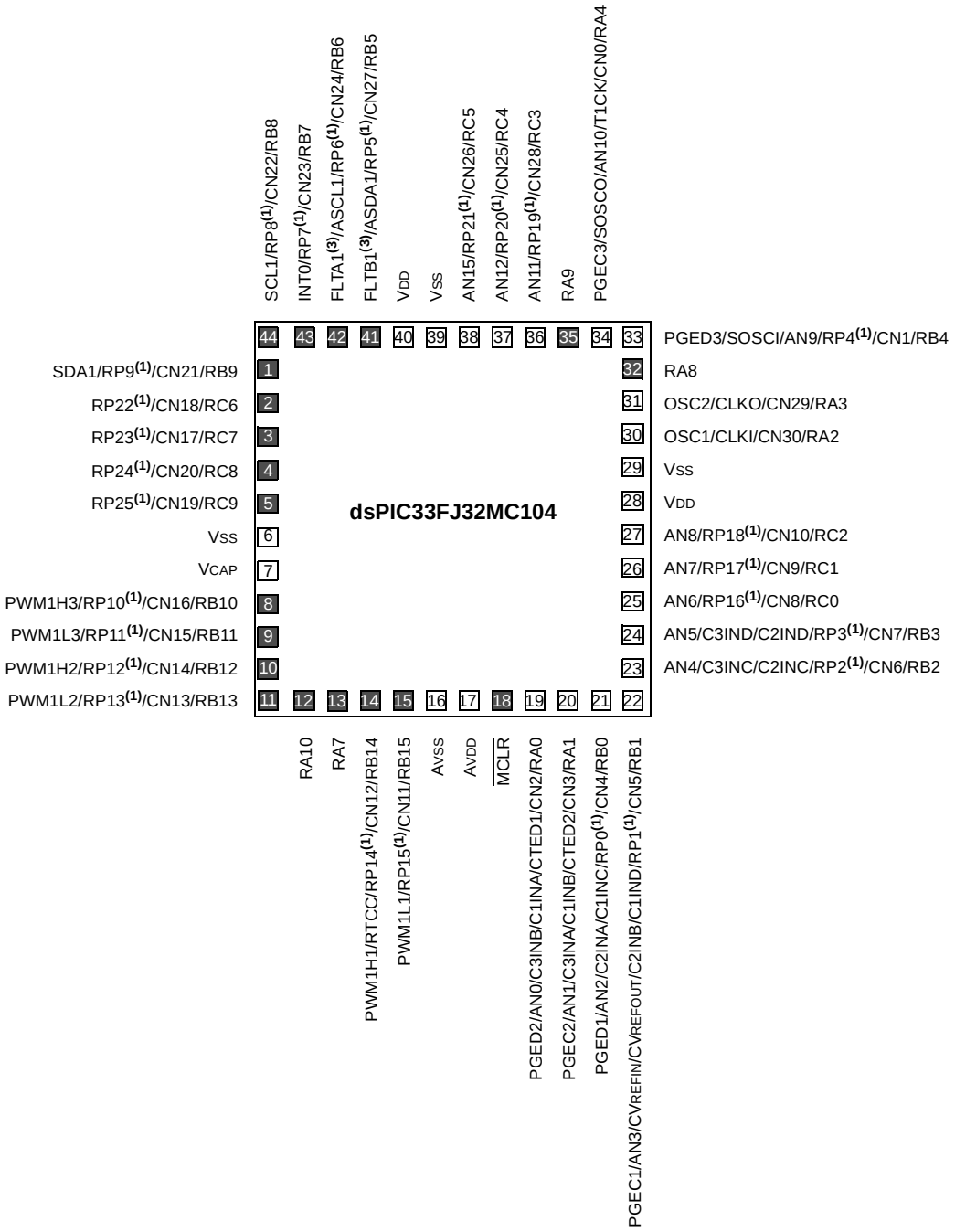
2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

3: The PWM Fault pins are enabled and asserted during any Reset event. Refer to **Section 15.2 "PWM Faults"** for more information on the PWM Faults.

Pin Diagrams (Continued)

44-Pin TLA(2)

■ = Pins are up to 5V tolerant

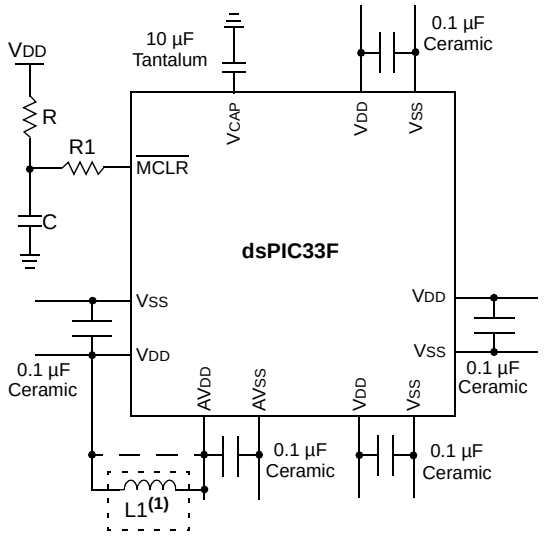


Note 1: The RPn pins can be used by any remappable peripheral. See Table 1 for the list of available peripherals.

2: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

3: The PWM Fault pins are enabled and asserted during any Reset event. Refer to **Section 15.2 "PWM Faults"** for more information on the PWM Faults.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 26.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 23.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

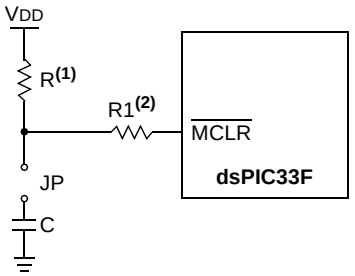
- Device Reset
- Device programming and debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor, C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

3.0 CPU

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 family devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"CPU"** (DS70204) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 CPU module has a 16-bit (data) modified Harvard architecture with an enhanced instruction set, including significant support for DSP. The CPU has a 24-bit instruction word with a variable length opcode field. The Program Counter (PC) is 23 bits wide and addresses up to 4M x 24 bits of user program memory space. The actual amount of program memory implemented varies by device. A single-cycle instruction prefetch mechanism is used to help maintain throughput and provides predictable execution. All instructions execute in a single cycle, with the exception of instructions that change the program flow, the double-word move (`MOV.D`) instruction and the table instructions. Overhead-free program loop constructs are supported using the `DO` and `REPEAT` instructions, both of which are interruptible at any point.

The dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices have sixteen, 16-bit Working registers in the programmer's model. Each of the Working registers can serve as a data, address, or address offset register. The 16th Working register (W15) operates as a Software Stack Pointer (SSP) for interrupts and calls.

There are two classes of instruction in the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices: MCU and DSP. These two instruction classes are seamlessly integrated into a single CPU. The instruction set includes many addressing modes and is designed for optimum C compiler efficiency. For most instructions, dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices are capable of executing a data (or program data) memory read, a Working register (data) read, a data memory write and a program (instruction) memory read per instruction cycle. As a result, three parameter instructions can be supported, allowing A + B = C operations to be executed in a single cycle.

A block diagram of the CPU is shown in Figure 3-1, and the programmer's model for the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 is shown in Figure 3-2.

3.1 Data Addressing Overview

The data space can be addressed as 32K words or 64 Kbytes and is split into two blocks, referred to as X and Y data memory. Each memory block has its own independent Address Generation Unit (AGU). The MCU class of instructions operates solely through the X memory AGU, which accesses the entire memory map as one linear data space. Certain DSP instructions operate through the X and Y AGUs to support dual operand reads, which splits the data address space into two parts. The X and Y data space boundary is device-specific.

Overhead-free circular buffers (Modulo Addressing mode) are supported in both X and Y address spaces. The Modulo Addressing removes the software boundary checking overhead for DSP algorithms. Furthermore, the X AGU circular addressing can be used with any of the MCU class of instructions. The X AGU also supports Bit-Reversed Addressing to greatly simplify input or output data reordering for radix-2 FFT algorithms.

The upper 32 Kbytes of the data space memory map can optionally be mapped into program space at any 16K program word boundary defined by the 8-bit Program Space Visibility Page (PSVPAG) register. The program-to-data-space mapping feature lets any instruction access program space as if it were data space.

3.2 DSP Engine Overview

The DSP engine features a high-speed, 17-bit by 17-bit multiplier, a 40-bit ALU, two 40-bit saturating accumulators and a 40-bit bidirectional barrel shifter. The barrel shifter is capable of shifting a 40-bit value up to 16 bits right or left, in a single cycle. The DSP instructions operate seamlessly with all other instructions and have been designed for optimal real-time performance. The `MAC` instruction and other associated instructions can concurrently fetch two data operands from memory, while multiplying two W registers and accumulating and optionally saturating the result in the same cycle. This instruction functionality requires that the RAM data space be split for these instructions and linear for all others. Data space partitioning is achieved in a transparent and flexible manner through dedicating certain Working registers to each address space.

3.4 CPU Control Registers

REGISTER 3-1: SR: CPU STATUS REGISTER

R-0	R-0	R/C-0	R/C-0	R-0	R/C-0	R-0	R/W-0
OA	OB	SA(1)	SB(1)	OAB	SAB	DA	DC
bit 15							bit 8

R/W-0(3)	R/W-0(3)	R/W-0(3)	R-0	R/W-0	R/W-0	R/W-0	R/W-0
IPL2(2)	IPL1(2)	IPL0(2)	RA	N	OV	Z	C
bit 7							bit 0

Legend:	C = Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **OA:** Accumulator A Overflow Status bit
1 = Accumulator A has overflowed
0 = Accumulator A has not overflowed

bit 14 **OB:** Accumulator B Overflow Status bit
1 = Accumulator B has overflowed
0 = Accumulator B has not overflowed

bit 13 **SA:** Accumulator A Saturation 'Sticky' Status bit(1)
1 = Accumulator A is saturated or has been saturated at some time
0 = Accumulator A is not saturated

bit 12 **SB:** Accumulator B Saturation 'Sticky' Status bit(1)
1 = Accumulator B is saturated or has been saturated at some time
0 = Accumulator B is not saturated

bit 11 **OAB:** OA || OB Combined Accumulator Overflow Status bit
1 = Accumulators A or B have overflowed
0 = Neither Accumulators A or B have overflowed

bit 10 **SAB:** SA || SB Combined Accumulator 'Sticky' Status bit
1 = Accumulators A or B are saturated or have been saturated at some time in the past
0 = Neither Accumulator A or B are saturated
This bit may be read or cleared (not set). *Clearing this bit will clear SA and SB*.

bit 9 **DA:** DO Loop Active bit
1 = DO loop is in progress
0 = DO loop is not in progress

bit 8 **DC:** MCU ALU Half Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred

Note 1: This bit can be read or cleared (not set).
2: The IPL<2:0> bits are concatenated with the IPL<3> bit (CORCON<3>) to form the CPU Interrupt Priority Level. The value in parentheses indicates the IPL if IPL<3> = 1. User interrupts are disabled when IPL<3> = 1.
3: The IPL<2:0> Status bits are read-only when NSTDIS = 1 (INTCON1<15>).

TABLE 4-1: CPU CORE REGISTER MAP (CONTINUED)

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CORCON	0044	—	—	—	US	EDT	DL2	DL1	DL0	SATA	SATB	SATDW	ACCSAT	IPL3	PSV	RND	IF	0020
MODCON	0046	XMODEN	YMODEN	—	—	BWM3	BWM2	BWM1	BWM0	YWM3	YWM2	YWM1	YWM0	XWM3	XWM2	XWM1	XWM0	0000
XMODSRT	0048	XS<15:1>															0	xxxx
XMODEND	004A	XE<15:1>															1	xxxx
YMODSRT	004C	YS<15:1>															0	xxxx
YMODEND	004E	YE<15:1>															1	xxxx
XBREV	0050	BREN	XB<14:0>															xxxx
DISICNT	0052	—	—	Disable Interrupts Counter Register														0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-9: INPUT CAPTURE REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
IC1BUF	0140	Input Capture 1 Register																xxxx
IC1CON	0142	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC2BUF	0144	Input Capture 2 Register																xxxx
IC2CON	0146	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000
IC3BUF	0148	Input Capture 3 Register																xxxx
IC3CON	014A	—	—	ICSIDL	—	—	—	—	—	ICTMR	ICI1	ICI0	ICOV	ICBNE	ICM2	ICM1	ICM0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-10: OUTPUT COMPARE REGISTER MAP

SFR Name	SFR Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1RS	0180	Output Compare 1 Secondary Register																xxxx
OC1R	0182	Output Compare 1 Register																xxxx
OC1CON	0184	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000
OC2RS	0186	Output Compare 2 Secondary Register																xxxx
OC2R	0188	Output Compare 2 Register																xxxx
OC2CON	018A	—	—	OCSIDL	—	—	—	—	—	—	—	—	OCFLT	OCTSEL	OCM2	OCM1	OCM0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-11: 6-OUTPUT PWM1 REGISTER MAP FOR dsPIC33FJXXMC10X DEVICES

SFR Name	SFR Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset State
P1TCON	01C0	PTEN	—	PTSIDL	—	—	—	—	—	PTOPS3	PTOPS2	PTOPS1	PTOPS0	PTCKPS1	PTCKPS0	PTMOD1	PTMOD0	0000 0000 0000 0000
P1TMR	01C2	PTDIR	PWM1 Timer Count Value Register															0000 0000 0000 0000
P1TPER	01C4	—	PWM1 Time Base Period Register															0111 1111 1111 1111
P1SECMP	01C6	SEVTDIR	PWM1 Special Event Compare Register															0000 0000 0000 0000
PWM1CON1	01C8	—	—	—	—	—	PMOD3	PMOD2	PMOD1	—	PEN3H	PEN2H	PEN1H	—	PEN3L	PEN2L	PEN1L	0000 0000 0000 0000
PWM1CON2	01CA	—	—	—	—	SEVOPS3	SEVOPS2	SEVOPS1	SEVOPS0	—	—	—	—	—	IUE	OSYNC	UDIS	0000 0000 0000 0000
P1DTCON1	01CC	DTBPS1	DTBPS0	DTB5	DTB4	DTB3	DTB2	DTB1	DTB0	DTAPS1	DTAPS0	DTA5	DTA4	DTA3	DTA2	DTA1	DTA0	0000 0000 0000 0000
P1DTCON2	01CE	—	—	—	—	—	—	—	—	—	—	DTS3A	DTS3I	DTS2A	DTS2I	DTS1A	DTS1I	0000 0000 0000 0000
P1FLTACON	01D0	—	—	FAOV3H	FAOV3L	FAOV2H	FAOV2L	FAOV1H	FAOV1L	FLTAM	—	—	—	—	FAEN3	FAEN2	FAEN1	0000 0000 0000 0111
P1FLTBCON	01D2	—	—	FBOV3H	FBOV3L	FBOV2H	FBOV2L	FBOV1H	FBOV1L	FLTBM	—	—	—	—	FBEN3	FBEN2	FBEN1	0000 0000 0000 0111
P1OVDCON	01D4	—	—	POVD3H	POVD3L	POVD2H	POVD2L	POVD1H	POVD1L	—	—	POUT3H	POUT3L	POUT2H	POUT2L	POUT1H	POUT1L	0011 1111 0000 0000
P1DC1	01D6	PWM1 Duty Cycle 1 Register																0000 0000 0000 0000
P1DC2	01D8	PWM1 Duty Cycle 2 Register																0000 0000 0000 0000
P1DC3	01DA	PWM1 Duty Cycle 3 Register																0000 0000 0000 0000
PWM1KEY	01DE	PWMKEY<15:0>																0000 0000 0000 0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 7-5: IFS0: INTERRUPT FLAG STATUS REGISTER 0 (CONTINUED)

bit 2 **OC1IF:** Output Compare Channel 1 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **IC1IF:** Input Capture Channel 1 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **INT0IF:** External Interrupt 0 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 7-14: IEC4: INTERRUPT ENABLE CONTROL REGISTER 4

U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
—	—	CTMUIE	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	U1EIE	FLTB1IE(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **CTMUIE:** CTMU Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 12-2 **Unimplemented:** Read as '0'

bit 1 **U1EIE:** UART1 Error Interrupt Enable bit
1 = Interrupt request is enabled
0 = Interrupt request is not enabled

bit 0 **FLTB1IE:** PWM1 Fault B Interrupt Enable bit(1)
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

Note 1: This bit is available in dsPIC(16/32)MC102/104 devices only.

8.2 Oscillator Control Registers

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER(1)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC2	COSC1	COSC0	—	NOSC2(2)	NOSC1(2)	NOSC0(2)
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	R/W-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN
bit 7							bit 0

Legend:	C = Clearable bit	y = Value set from Configuration bits on POR	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC Oscillator (FRC) with Divide-by-n
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator (MS, EC) with PLL
010 = Primary Oscillator (MS, HS, EC)
001 = Fast RC Oscillator (FRC) with Divide-by-n and PLL (FRCPLL)
000 = Fast RC Oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC Oscillator (FRC) with Divide-by-n
110 = Fast RC Oscillator (FRC) with Divide-by-16
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator (MS, EC) with PLL
010 = Primary Oscillator (MS, HS, EC)
001 = Fast RC Oscillator (FRC) with Divide-by-n and PLL (FRCPLL)
000 = Fast RC Oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
If Clock Switching is Enabled and FSCM is Disabled (FCKSM<1:0> (FOSC<7:6>) = 0b01):
1 = Clock switching is disabled, system clock source is locked
0 = Clock switching is enabled, system clock source can be modified by clock switching

bit 6 **IOLOCK:** Peripheral Pin Select Lock bit
1 = Peripheral Pin Select is locked, a write to Peripheral Pin Select registers is not allowed
0 = Peripheral Pin Select is not locked, a write to Peripheral Pin Select registers is allowed

bit 5 **LOCK:** PLL Lock Status bit (read-only)
1 = Indicates that PLL is in lock or PLL start-up timer is satisfied
0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

Note 1: Writes to this register require an unlock sequence. Refer to **"Oscillator (Part VI)"** (DS70644) in the *"dsPIC33/PIC24 Family Reference Manual"* for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transitional clock source between the two PLL modes.

15.2 PWM Faults

The Motor Control PWM module incorporates up to two Fault inputs, FLTA1 and FLTB1. These Fault inputs are implemented with Class B safety features. These features ensure that the PWM outputs enter a safe state when either of the Fault inputs is asserted.

The FLTA1 and FLTB1 pins, when enabled and having ownership of a pin, also enable a soft internal pull-down resistor. The soft pull-down provides a safety feature by automatically asserting the Fault should a break occur in the Fault signal connection.

The implementation of internal pull-down resistors is dependent on the device variant. Table 15-1 describes which devices and pins implement the internal pull-down resistors.

TABLE 15-1: INTERNAL PULL-DOWN RESISTORS ON PWM FAULT PINS

Device	Fault Pin	Internal Pull-Down Implemented?
dsPIC33FJXXMC101	FLTA1	No
dsPIC33FJXXMC102	FLTA1	Yes
	FLTB1	Yes
dsPIC33FJ32MC104	FLTA1	Yes
	FLTB1	Yes

On devices without internal pull-downs on the Fault pin, it is recommended to connect an external pull-down resistor for Class B safety features.

15.2.1 PWM FAULTS AT RESET

During any Reset event, the PWM module maintains ownership of both PWM Fault pins. At Reset, both Faults are enabled in latched mode to guarantee the fail-safe power-up of the application. The application software must clear both of the PWM Faults before enabling the Motor Control PWM module.

The Fault condition must be cleared by the external circuitry driving the Fault input pin high and clearing the Fault interrupt flag. After the Fault pin condition has been cleared, the PWM module restores the PWM output signals on the next PWM period or half-period boundary.

Refer to **"Motor Control PWM"** (DS70187) in the "*dsPIC33/PIC24 Family Reference Manual*" for more information on the PWM Faults.

Note:	The number of PWM Faults mapped to the device pins depend on the specific variant. Regardless of the variant, both Faults will be enabled during any Reset event. The application must clear both FLTA1 and FLTB1 before enabling the Motor Control PWM module. Refer to the specific device pin diagrams to see which Fault pins are mapped to the device pins.

15.3 Write-Protected Registers

On dsPIC33FJ(16/32)MC10X devices, write protection is implemented for the PWMxCON1, PxFLTACON and PxFLTBCON registers. The write protection feature prevents any inadvertent writes to these registers. The write protection feature can be controlled by the PWMLOCK Configuration bit in the FOSCSEL Configuration register. The default state of the write protection feature is enabled (PWMLOCK = 1). The write protection feature can be disabled by configuring PWMLOCK (FOSCSEL<6>) = 0.

The user application can gain access to these locked registers either by configuring the PWMLOCK bit (FOSCSEL<6>) = 0 or by performing the unlock sequence. To perform the unlock sequence, the user application must write two consecutive values (0xABCD and 0x4321) to the PWMxKEY register to perform the unlock operation. The write access to the PWMxCON1, PxFLTACON or PxFLTBCON registers must be the next SFR access following the unlock process. There can be no other SFR accesses during the unlock process and subsequent write access.

To write to all registers, the PWMxCON1, PxFLTACON and PxFLTBCON registers require three unlock operations.

The correct unlocking sequence is described in Example 15-1 and Example 15-2.

REGISTER 17-2: I2CxSTAT: I2Cx STATUS REGISTER (CONTINUED)

bit 4 **P:** Stop bit
1 = Indicates that a Stop bit has been detected last
0 = Stop bit was not detected last
Hardware sets or clears when Start, Repeated Start or Stop is detected.

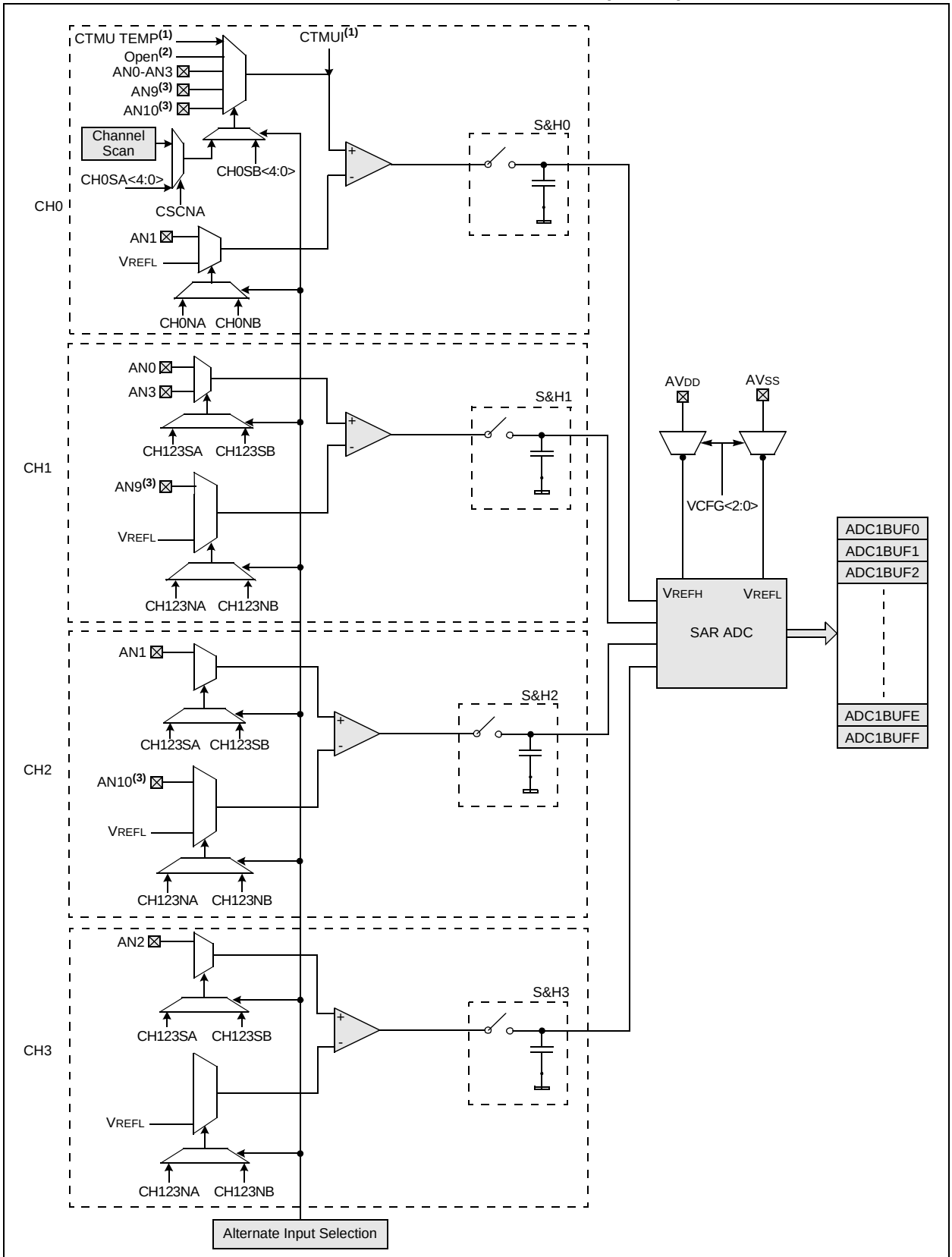
bit 3 **S:** Start bit
1 = Indicates that a Start (or Repeated Start) bit has been detected last
0 = Start bit was not detected last
Hardware sets or clears when Start, Repeated Start or Stop is detected.

bit 2 **R_W:** Read/Write Information bit (when operating as I^2C slave)
1 = Read – Indicates data transfer is output from slave
0 = Write – Indicates data transfer is input to slave
Hardware sets or clears after reception of an I^2C device address byte.

bit 1 **RBF:** Receive Buffer Full Status bit
1 = Receive is complete, I2CxRCV is full
0 = Receive is not complete, I2CxRCV is empty
Hardware sets when I2CxRCV is written with received byte. Hardware clears when software reads I2CxRCV.

bit 0 **TBF:** Transmit Buffer Full Status bit
1 = Transmit in progress, I2CxTRN is full
0 = Transmit complete, I2CxTRN is empty
Hardware sets when software writes to I2CxTRN. Hardware clears at completion of data transmission.

FIGURE 19-1: ADC1 BLOCK DIAGRAM FOR dsPIC33FJXX(GP/MC)101 DEVICES



Note 1: Internally connected to the CTMU module.
2: This selection is only used with CTMU capacitive and time measurement.
3: This pin is available in dsPIC33FJ32(GP/MC)101 devices only.

22.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note 1: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 device families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Charge Time Measurement Unit (CTMU)"** (DS70635) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Charge Time Measurement Unit (CTMU) is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Four edge input trigger sources
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- Precise time measurement resolution of 200 ps
- Accurate current source suitable for capacitive measurement
- On-chip temperature measurement using a built-in diode

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors. The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 enables the module, the edge delay generation, sequencing of edges, and controls the current source and the output trigger. CTMUCON2 controls the edge source selection, edge source polarity selection and edge sampling mode. The CTMUICON register controls the selection and trim of the current source.

Figure 22-1 shows the CTMU block diagram.

TABLE 23-4: dsPIC33F CONFIGURATION BITS DESCRIPTION (CONTINUED)

Bit Field	Description
WDTPRE	Watchdog Timer Prescaler bit 1 = 1:128 0 = 1:32
WDTPOST<3:0>	Watchdog Timer Postscaler bits 1111 = 1:32,768 1110 = 1:16,384 • • • 0001 = 1:2 0000 = 1:1
PLLKEN	PLL Lock Enable bit 1 = Clock switch to PLL will wait until the PLL lock signal is valid 0 = Clock switch will not wait for the PLL lock signal
ALTI2C	Alternate I^2C™ Pins bit 1 = I^2C is mapped to SDA1/SCL1 pins 0 = I^2C is mapped to ASDA1/ASCL1 pins
ICS<1:0>	ICD Communication Channel Select bits 11 = Communicate on PGEC1 and PGED1 10 = Communicate on PGEC2 and PGED2 01 = Communicate on PGEC3 and PGED3 00 = Reserved, do not use
PWMPIN	Motor Control PWM Module Pin Mode bit 1 = PWM module pins controlled by PORT register at device Reset (tri-stated) 0 = PWM module pins controlled by PWM module at device Reset (configured as output pins)
HPOL	Motor Control PWM High Side Polarity bit 1 = PWM module high side output pins have active-high output polarity 0 = PWM module high side output pins have active-low output polarity
LPOL	Motor Control PWM Low Side Polarity bit 1 = PWM module low side output pins have active-high output polarity 0 = PWM module low side output pins have active-low output polarity

24.0 INSTRUCTION SET SUMMARY

Note: This data sheet summarizes the features of the dsPIC33FJ16(GP/MC)101/102 and dsPIC33FJ32(GP/MC)101/102/104 devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the latest family reference sections of the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com).

The dsPIC33F instruction set is identical to that of the dsPIC30F.

Most instructions are a single program memory word (24 bits). Only three instructions require two program memory locations.

Each single-word instruction is a 24-bit word, divided into an 8-bit opcode, which specifies the instruction type and one or more operands, which further specify the operation of the instruction.

The instruction set is highly orthogonal and is grouped into five basic categories:

- Word or byte-oriented operations
- Bit-oriented operations
- Literal operations
- DSP operations
- Control operations

Table 24-1 shows the general symbols used in describing the instructions.

The dsPIC33F instruction set summary in Table 24-2 lists all the instructions, along with the status flags affected by each instruction.

Most word or byte-oriented W register instructions (including barrel shift instructions) have three operands:

- The first source operand, which is typically a register 'Wb' without any address modifier
- The second source operand, which is typically a register 'Ws' with or without an address modifier
- The destination of the result, which is typically a register 'Wd' with or without an address modifier

However, word or byte-oriented file register instructions have two operands:

- The file register specified by the value 'f'
- The destination, which could be either the file register 'f' or the W0 register, which is denoted as 'WREG'

Most bit-oriented instructions (including simple rotate/shift instructions) have two operands:

- The W register (with or without an address modifier) or file register (specified by the value of 'Ws' or 'f')
- The bit in the W register or file register (specified by a literal value or indirectly by the contents of register 'Wb')

The literal instructions that involve data movement can use some of the following operands:

- A literal value to be loaded into a W register or file register (specified by 'k')
- The W register or file register where the literal value is to be loaded (specified by 'Wb' or 'f')

However, literal instructions that involve arithmetic or logical operations use some of the following operands:

- The first source operand, which is a register 'Wb' without any address modifier
- The second source operand, which is a literal value
- The destination of the result (only if not the same as the first source operand), which is typically a register 'Wd' with or without an address modifier

The MAC class of DSP instructions can use some of the following operands:

- The accumulator (A or B) to be used (required operand)
- The W registers to be used as the two operands
- The X and Y address space prefetch operations
- The X and Y address space prefetch destinations
- The accumulator write-back destination

The other DSP instructions do not involve any multiplication and can include:

- The accumulator to be used (required)
- The source or destination operand (designated as Wso or Wdo, respectively) with or without an address modifier
- The amount of shift specified by a W register 'Wn' or a literal value

The control instructions can use some of the following operands:

- A program memory address
- The mode of the Table Read and Table Write instructions

TABLE 26-44: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 0, SMP = 0) TIMING REQUIREMENTS FOR dsPIC33FJ32(GP/MC)10X

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscP	Maximum SCKx Input Frequency	—	—	11	MHz	See **Note 3**
SP72	TscF	SCKx Input Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP73	TscR	SCKx Input Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP30	TdoF	SDOx Data Output Fall Time	—	—	—	ns	See Parameter DO32 and **Note 4**
SP31	TdoR	SDOx Data Output Rise Time	—	—	—	ns	See Parameter DO31 and **Note 4**
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	6	20	ns	
SP36	TdoV2scH, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	30	—	—	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	30	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance	10	—	50	ns	See **Note 4**
SP52	TscH2ssH TscL2ssH	$\overline{SSx}$ after SCKx Edge	1.5 TCY + 40	—	—	ns	See **Note 4**

Note 1: These parameters are characterized, but are not tested in manufacturing.

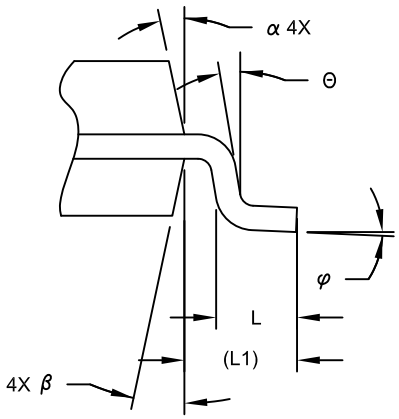
2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: The minimum clock period for SCKx is 91 ns. Therefore, the SCKx clock generated by the Master must not violate this specification.

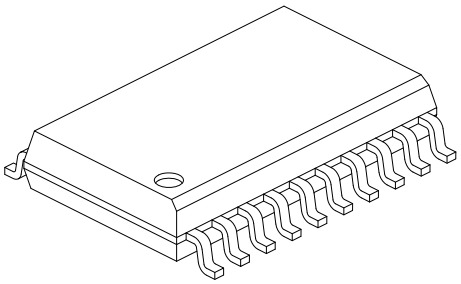
4: Assumes 50 pF load on all SPIx pins.

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		20	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		12.80 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.20	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

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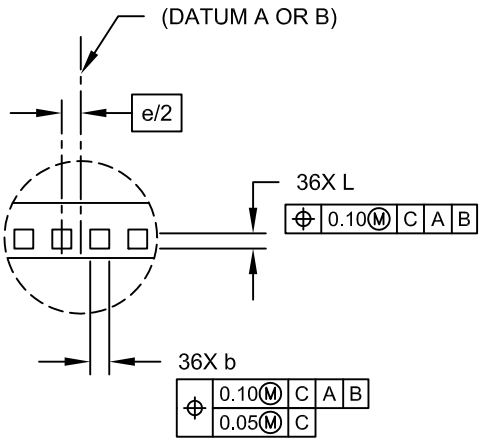
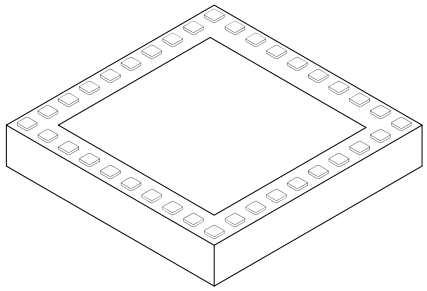
36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

NOTES: